300mm Fully-Automatic Multifunction Wafer Mounter

RAD-2510F/12Sa

Outline

- Fully-automatic wafer mounter suited for ultra-thin wafer manufacturing, with the following functions:
  - UV irradiation to BG Tape
  - Alignment
  - Wafer mounting
  - BG Tape peeling
- Ability to operate in-line with DISCO Corporation’s DFG8000 series back grinder or DGP8000 series grinder/polisher.
- Corresponds to DBG process.
- Prevents wafer damage by reducing wafer handling frequency down to 4 times "stand-alone," and 2 times "in-line."

Options

- Host Communication Function (Communication Format: Conforms to SECS-I and HSMS/Software: Conforms to GEM)
- Vision System (Wafer ID Reader & Barcode Attachment System)
- Dicing Tape In-line Pre-cutting
- DBG Process Compatibility
- In-line Operation with DISCO Corporation DFG8000 series or DGP8000 series

Suitable Tapes

- Dicing tape: Adwill D series, G series
- Dicing die bonding tape: Adwill LE Tape

Facility

<table>
<thead>
<tr>
<th>Facility</th>
<th>Value</th>
</tr>
</thead>
<tbody>
<tr>
<td>Power Supply Voltage</td>
<td>200V (±10%)</td>
</tr>
<tr>
<td>Frequency</td>
<td>50/60Hz</td>
</tr>
<tr>
<td>Phase</td>
<td>3 phase</td>
</tr>
<tr>
<td>Power consumption</td>
<td>8.0kW (200VAC)</td>
</tr>
<tr>
<td>Air Supply Air pressure</td>
<td>0.6-0.8MPa</td>
</tr>
<tr>
<td>Air consumption</td>
<td>&gt;800L/min (ANR)</td>
</tr>
<tr>
<td>Vacuum Supply Vacuum pressure</td>
<td>&gt;-80kPa</td>
</tr>
</tbody>
</table>

Applicable Wafer Size

200mm, 300mm

Size

- Width: 2,165mm
- Depth: 3,090mm
- Height: 1,800mm

(excluding the signal tower and protruding parts)

Weight

3,100kg

UPH

45 wafers/hour

The above processing capacity is based on following conditions ("stand-alone"):

- Wafer: 300mm diameter non-polished mirror wafer
- Ring frame: for 300mm wafer
- Dicing tape: G-18 from LINTEC
- Back grinding tape: E-8180HR from LINTEC

External View

Unit:mm

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